July 13, 2016

Invensas Wins 2016 3D InCites Supplier of the Year Award

Award Recognizes Leading Edge Zibond® and DBI® Bonding & Interconnect Technologies

SAN JOSE, Calif.--(BUSINESS WIRE)-- Tessera Technologies, Inc. (Nasdaq: TSRA), announced today that its wholly owned subsidiary Invensas Corporation received the 2016 3D InCites Supplier of the Year and Fabless of the Year Awards. These awards were presented at SEMICON West on July 12 by 3D InCites and Impress Foundation at the fourth annual celebration to honor the industry's best 3D IC companies, solutions and achievements.

"We are honored to be named winners in both the Supplier of the Year and Fabless of the Year categories of this competition," said Craig Mitchell, president, Invensas. "Our 3D integration platforms are in high volume production today and we believe will be essential to next-generation high-performance logic, memory, MEMS and image sensor solutions."

The 3D InCites Awards were established in 2013 to recognize achievements that further the commercialization of interposer and 3D integration technologies. In 2015, many of these technologies became productized, and are being recognized as part of the overall advanced packaging landscape for the value they bring to today's electronic devices**.**

"Invensas has clearly demonstrated its 3D IC vision and its ability to develop and bring advanced new solutions to market," said Françoise von Trapp, founder of 3D InCites. "This is a banner year for 3D integration and packaging, and it has been encouraging to see these technologies feature so prominently at SEMICON West."

For more information on Invensas and Invensas solutions, please visit www.invensas.com or www.tessera.com.

About Tessera Technologies, Inc.

Tessera Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and computational imaging and computer vision products and solutions for mobile and other vision systems. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

About 3D InCites

3D InCites is the fastest growing online resource devoted exclusively to interposer integration 3D IC, and 3D heterogeneous integration technologies. For 3D integration to happen requires open collaboration across the supply chain. Therefore, 3D InCites strives to inform key decision makers about progress in technology development, design, standards, and infrastructure in order to realize commercial production of interposer integration and 3D IC technologies. For more information visit www.3DinCites.com.

Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the potential future uses of 3D IC technologies in next generation solutions. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015 and its Quarterly Report on Form 10-Q for the quarter ended Mar. 31, 2016, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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